

ABSTRACT OF THE DISCLOSURE

An abrasive molding consisting essentially of inorganic particles having an average particle diameter in the range of 0.005 μm to 0.3 μm , and having a relative density in the range of 45% to 90%, provided that pores having a diameter of at least 0.5 μm are excluded from the molding. The abrasive molding is used for polishing a material to be polished by using a polishing liquid, preferably water or an aqueous solution of an alkali metal hydroxide, which does not contain a loose abrasive grain.